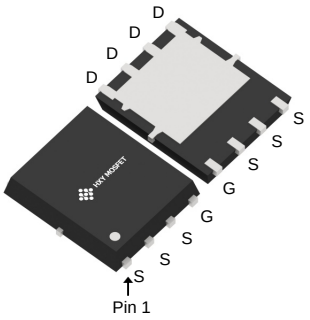
SI7155DP-T1-GE3

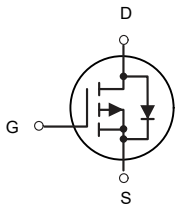
P-Channel Enhancement Mode MOSFET

Description

The SI7155DP-T1-GE3 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



DFN5X6-8L



P-Channel MOSFET

General Features

V_{DS} = -40V I_D =-100A

$R_{DS(ON)}$ < 4.1 mΩ V_{GS}=-10V

Application

Battery protection

Load switch

Uninterruptible power supply

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
SI7155DP-T1-GE3	DFN5X6-8L	HXY MOSFET	5000

Absolute Maximum Ratings (T_C=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-40	V
V_{GS}	Gate-Source Voltage	±20	V
I_D@T_C=25°C	Continuous Drain Current, V_{GS} @ 10V	-100	A
I_D@T_C=100°C	Continuous Drain Current, V_{GS} @ 10V	-70	A
I_{DM}	Pulsed Drain Current[2]	-400	A
EAS	Single Pulse Avalanche Energy[3]	1225	mJ
P_D@T_C=25°C	Total Power Dissipation[4]	200	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta Jc}$	Thermal Resistance,Junction-to-Case	0.95	°C/W

Electrical Characteristics (T_J = 25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=-250uA	-40	---	---	V
$\triangle BV_{DSS}/\triangle T_J$	BV_{DSS} Temperature Coefficient	Reference to 25℃ , I_D=-1mA	---	---	---	V/℃
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=-10V , I_D=-13A	---	3.1	4.1	mΩ
		V_{GS}=-4.5V , I_D=-13A	---	4.4	5.4	
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =-250uA	-1.2	---	-2.5	V
$\triangle V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	---	---	mV/℃
I_{DSS}	Drain-Source Leakage Current	V_{DS}=-40V , V_{GS}=0V , T_J=25°C	---	---	-1	uA
		V_{DS}=-40V , V_{GS}=0V , T_J=55°C	---	---	-100	
I_{GSS}	Gate-Source Leakage Current	V_{GS}= ±20V , V_{DS}=0V	---	---	±100	nA
gfs	Forward Transconductance	V_{DS}=-10V , I_D=-13A	---	51	---	S
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	1.7	---	Ω
Q_g	Total Gate Charge	V_{DS}=-20V , V_{GS}=-10V , I_D=-13A	---	195	---	nC
Q_{gs}	Gate-Source Charge		---	24.1	---	
Q_{gd}	Gate-Drain Charge		---	39.9	---	
$T_{d(on)}$	Turn-On Delay Time	V_{DD}=-20V , V_{GS}=-10V , R_G=3.3Ω	---	19.6	---	ns
T_r	Rise Time		---	3.6	---	
$T_{d(off)}$	Turn-Off Delay Time		---	22.8	---	
T_f	Fall Time		---	38	---	
C_{iss}	Input Capacitance	V_{DS}=-20V , V_{GS}=0V , f=1MHz	---	10733	---	pF
C_{oss}	Output Capacitance		---	770	---	
C_{rss}	Reverse Transfer Capacitance		---	697	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current[1,4]	V_G=V_D=0V , Force Current	---	---	-100	A
V_{SD}	Diode Forward Voltage[2]	V_{GS}=0V , I_S=-13A , T_J=25°C	---	---	-1.2	V
t_{rr}	Reverse Recovery Time	IF=-13A , di/dt=100A/μs , T_J=25°C	---	51.1	---	nS
Q_{rr}	Reverse Recovery Charge		---	125.2	---	nC

Note :
1.The data tested by surface mounted on a 1 inch^2 FR-4 board with 2OZ copper.
2.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%
3.The EAS data shows Max. rating . The test condition is TJ=25℃,VDD=-40V,VG=-10V, Rg=25Ω, L=0.5mH.
4.The power dissipation is limited by 150℃ junction temperature
5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Performance Characteristics

Figure 1. Output Characteristics

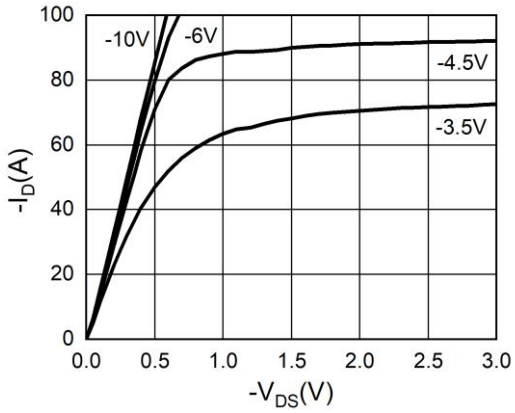


Figure 2. Transfer Characteristics

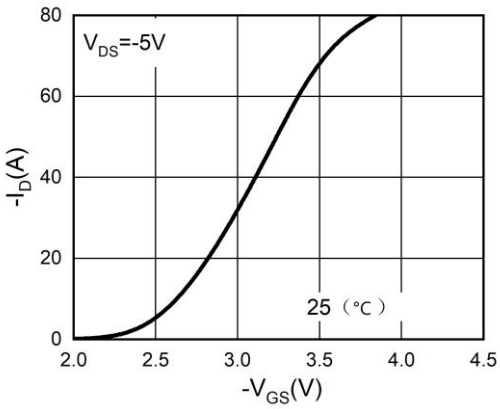


Figure 3. Power Dissipation

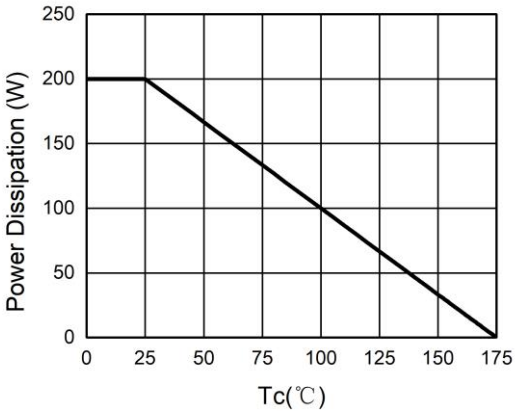


Figure 4. Drain Current

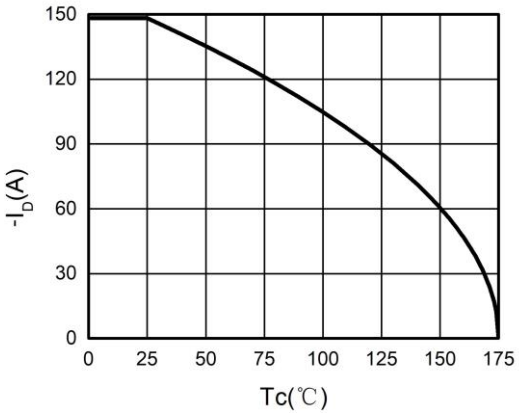


Figure 5. BV_{DSS} vs Junction Temperature

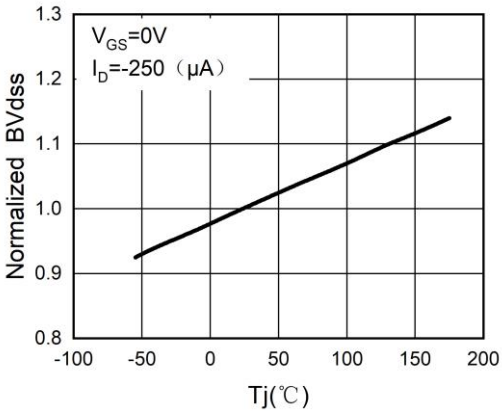


Figure 6. $R_{DS(ON)}$ vs Junction Temperature

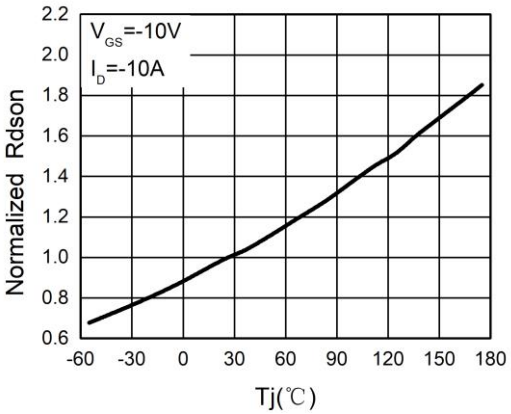


Figure 7. Gate Charge Waveforms

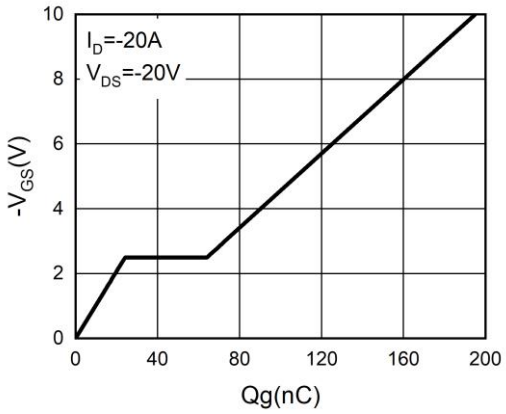


Figure 8. Capacitance

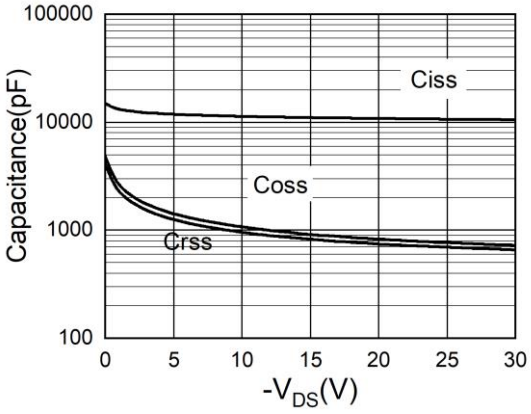


Figure 9. Body-Diode Characteristics

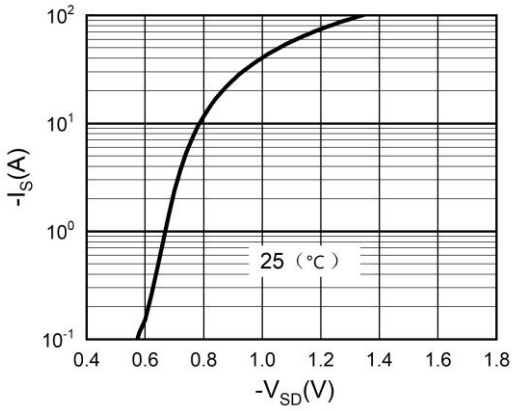
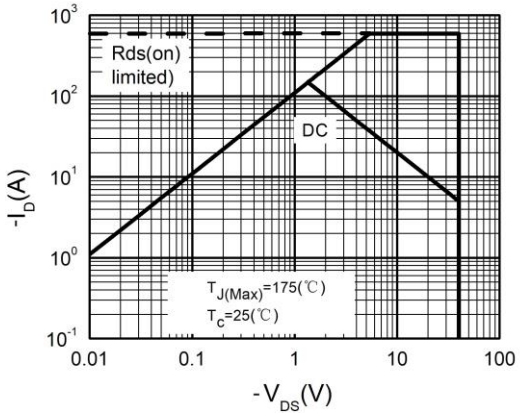
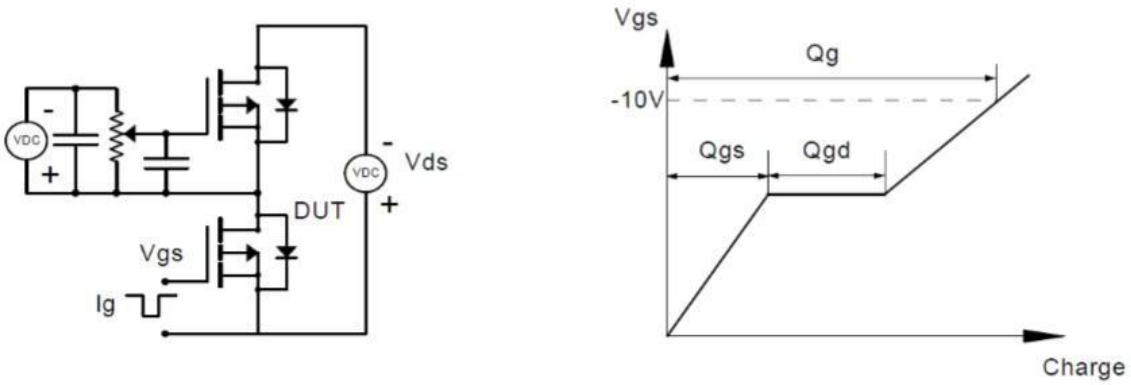


Figure 10. Maximum Safe Operating Area

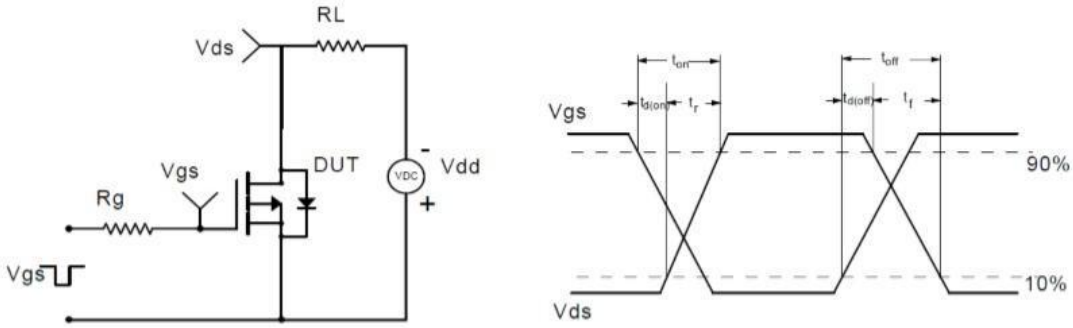


Test Circuit

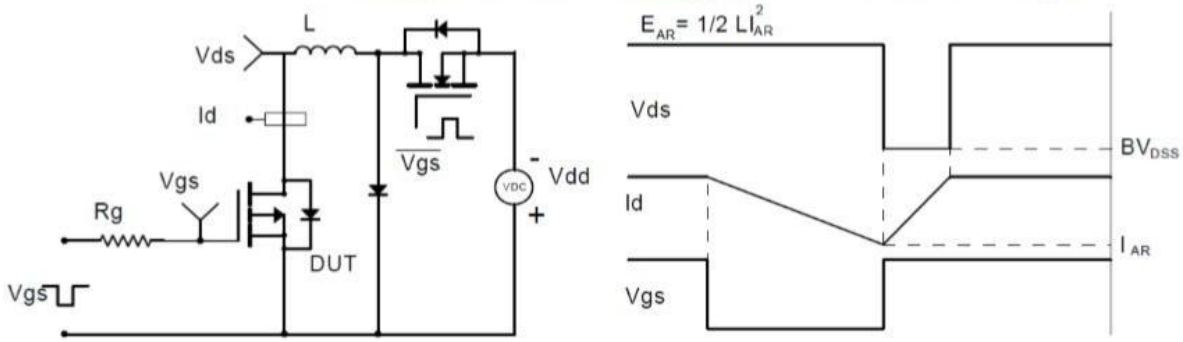
Gate Charge Test Circuit & Waveform



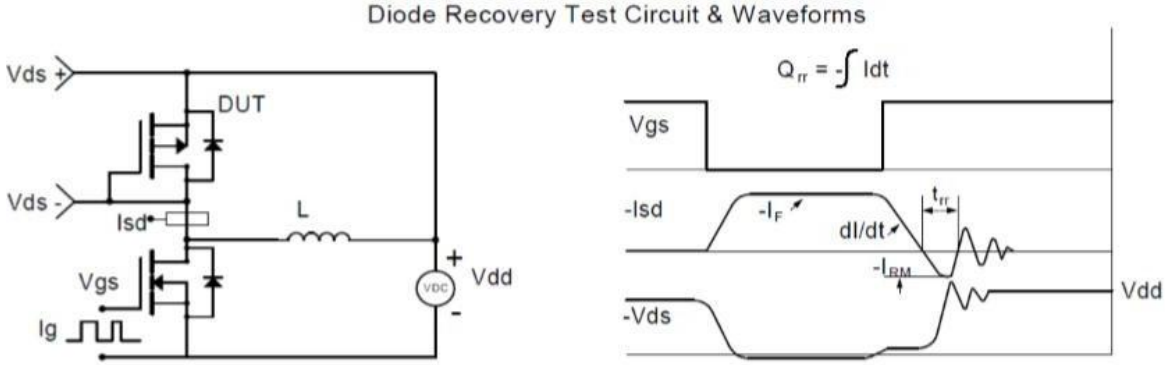
Resistive Switching Test Circuit & Waveforms



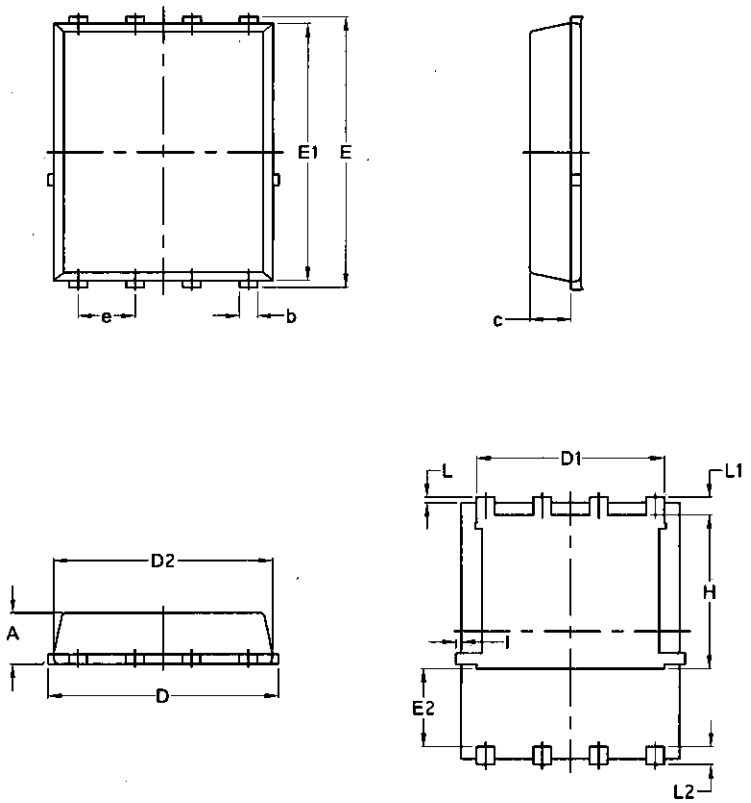
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



DFN5X6-8L Package Information



Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070

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